Asisa Kumar Panigrahi

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

47	365	12	17
papers	citations	h-index	g-index
54	525	2.1	3.87
ext. papers	ext. citations	avg, IF	L-index

#	Paper	IF	Citations
47	An extensive survey on reduction of noise coupling in TSV based 3D IC integration. *Materials Today: Proceedings*, **2021**, 45, 1471-1480	1.4	0
46	An automated detection of heart arrhythmias using machine learning technique: SVM. *Materials Today: Proceedings*, **2021**, 45, 1393-1398	1.4	8
45	Thermal management in TSV based 3D IC Integration: A survey. *Materials Today: Proceedings*, **2021**, 45, 1742-1746	1.4	0
44	Simplistic approach to reduce thermal issues in 3D IC integration technology. *Materials Today: Proceedings*, **2021**, 45, 1399-1402	1.4	1
43	Design of area-efficient high speed 4 4 Wallace tree multiplier using quantum-dot cellular automata. *Materials Today: Proceedings*, **2021**, 45, 1514-1523	1.4	
42	An extensive survey on finger and palm vein recognition system. *Materials Today: Proceedings*, **2021** , 45, 1804-1808	1.4	3
41	Performance evaluation of noise coupling on Germanium based TSV filled material for future IC integration technique. *Materials Today: Proceedings*, **2021**, 45, 1494-1497	1.4	2
40	Recent developments in code compression techniques for embedded systems. *Materials Today: Proceedings*, **2021**, 46, 4128-4132	1.4	0
39	Facile approach to mitigate thermal issues in 3D IC integration using effective FIN orientation. *Materials Today: Proceedings*, **2020**, 33, 3085-3088	1.4	5
38	Sleep Bruxism Disorder Detection and Feature Extraction Using Discrete Wavelet Transform. *Lecture Notes in Electrical Engineering*, **2020**, 833-840	0.2	5
37	Feature Extraction and Detection of Obstructive Sleep Apnea from Raw EEG Signal. *Advances in Intelligent Systems and Computing*, **2020**, 425-433	0.4	5
36	Simplistic approach to alleviate noise coupling issues in 3D IC integration. *Materials Today: Proceedings*, **2020**, 33, 4007-4011	1.4	4
35	Noise performance improvement in 3D IC integration utilizing different dielectric materials. *Materials Today: Proceedings*, **2020**, 33, 3117-3123	1.4	4
34	Hand gesture recognition and voice controlled robot. *Materials Today: Proceedings*, **2020**, 33, 4121-4123	1.4	4
33	Diffusion Enhanced Drive Sub 100 C Wafer Level Fine-Pitch Cu-Cu Thermocompression Bonding for 3D IC Integration **2019**,		2
32	Interface and Reliability Analysis of Au-Passivated Cu u Fine-Pitch Thermocompression Bonding for 3-D IC Applications. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2019**, 9, 1227-1234	1.7	15
31	. *IEEE Transactions on Device and Materials Reliability*, **2019**, 19, 791-795	1.6	8

30	Revival of cloaking effect in a driven bilayer graphene vector barrier. *Physica E: Low-Dimensional Systems and Nanostructures*, **2018**, 99, 330-334	3	1
29	Direct, CMOS In-Line Process Flow Compatible, Sub 100 �C Cu�Cu Thermocompression Bonding Using Stress Engineering. *Electronic Materials Letters*, **2018**, 14, 328-335	2.9	12
28	Optimized ultra-thin manganin alloy passivated fine-pitch damascene compatible bump-less Cu�Cu bonding at sub 200 �C for three-dimensional Integration applications. *Japanese Journal of Applied Physics*, **2018**, 57, 02BC04	1.4	6
27	Vanadium Pentoxide Nanofibers as IR Sensors for Bolometer Applications. *ECS Transactions*, **2018**, 85, 1573-1583	1	1
26	Metal-Alloy Cu Surface Passivation Leads to High Quality Fine-Pitch Bump-Less Cu-Cu Bonding for 3D IC and Heterogeneous Integration Applications **2018**,		6
25	Low Temperature Cu�Cu Bonding Technology in Three-Dimensional Integration: An Extensive Review. *Journal of Electronic Packaging, Transactions of the ASME*, **2018**, 140,	2	26
24	Oxidation Resistive, CMOS Compatible Copper-Based Alloy Ultrathin Films as a Superior Passivation Mechanism for Achieving 150 �C Cu�Cu Wafer on Wafer Thermocompression Bonding. *IEEE Transactions on Electron Devices*, **2017**, 64, 1239-1245	2.9	20
23	Demonstration of sub 150 �C Cu-Cu thermocompression bonding for 3D IC applications, utilizing an ultra-thin layer of Manganin alloy as an effective surface passivation layer. *Materials Letters*, **2017**, 194, 86-89	3.3	29
22	A multi-walled carbon nanotube-zinc oxide nanofiber based flexible chemiresistive biosensor for malaria biomarker detection. *Analyst, The*, **2017**, 142, 2128-2135	5	39
21	Nonlithographic Fabrication of Plastic-Based Nanofibers Integrated Microfluidic Biochip for Sensitive Detection of Infectious Biomarker. *ACS Applied Materials & Interfaces*, **2017**, 9, 39994-40005	9.5	15
20	**2017**,		2
19	**2017**,		4
18	High Quality Fine-Pitch Cu-Cu Wafer-on-Wafer Bonding with Optimized Ti Passivation at 160�C **2016**,		6
17	Analysis of graphene and CNT based finned TTSV and spreaders for thermal management in 3D IC **2016**,		5
16	Noise performance improvement through optimized stacked layer of liner structure around the TSV in 3D IC **2016**,		2
15	Ultra-thin Ti passivation mediated breakthrough in high quality Cu-Cu bonding at low temperature and pressure. *Materials Letters*, **2016**, 169, 269-272	3.3	29
14	Improved noise coupling performance using optimized Teflon liner with different TSV structures for 3D IC integration **2016**,		3
13	Facile non thermal plasma based desorption of self assembled monolayers for achieving low temperature and low pressure Cu�Cu thermo-compression bonding. *RSC Advances*, **2015**, 5, 103643-103648	3.7	20

12	Low temperature, low pressure CMOS compatible Cu -Cu thermo-compression bonding with Ti passivation for 3D IC integration **2015**,		12
11	Long term efficacy of ultra-thin Ti passivation layer for achieving low temperature, low pressure Cu-Cu Wafer-on-Wafer bonding **2015**,		3
10	Design and Modelling of Highly Sensitive Glucose Biosensor for Lab-on-chip Applications. *Silicon*,1	2.4	9
9	A Novel Teeth Junction Less Gate All Around FET for Improving Electrical Characteristics. *Silicon*,1	2.4	15
8	An energy-efficient reconfigurable accelerators in multi-core systems using PULP-NN. *Applied Nanoscience (Switzerland)*,1	3.3	2
7	Enhancement in performance of DHTprecoding over WHT for EC companded OFDM in wireless networks. *Applied Nanoscience (Switzerland)*,1	3.3	2
6	A Study of an Ultrasensitive Label Free Silicon Nanowire FET Biosensor for Cardiac Troponin I Detection. *Silicon*,1	2.4	13
5	Performance Analysis of Ion-Sensitive Field Effect Transistor with Various Oxide Materials for Biomedical Applications. *Silicon*,1	2.4	13
4	Tunnel Field Effect Transistor Design and Analysis for Biosensing Applications. *Silicon*,1	2.4	1
3	Temperature Influence on Dielectric Tunnel FET Characterization and Subthreshold Characterization. *Silicon*,1	2.4	1
2	A Highly Sensitive Graphene-based Field Effect Transistor for the Detection of Myoglobin. *Silicon*,1	2.4	1
1	Design of approximate reverse carry select adder using RCPA. *International Journal of Electronics Letters*,1-11	0.6	1